

CxO Summit

Welcome Remarks

L. Altimime
President
SEMI Europe, Berlin, Germany



Abstract

Welcome Remarks

Biography

Laith Altimime, as President of SEMI Europe, leads SEMI's activities in Europe and the Middle East and Africa (EMEA). Altimime has P&L responsibility as well as ownership of all Europe region programs and events, including SEMICON Europa. He is responsible for establishing industry standards, advocacy, community development, expositions, and programs. He provides support and services to SEMI members worldwide that have supply chain interests in Europe. He manages and nurtures relationships with SEMI members in the region and globally as well as with local associations and constituents in industry, government, and academia. Altimime has more than 30 years of international experience in the semiconductor industry. Prior to joining SEMI in 2015, He held senior leadership positions at NEC, KLA-Tencor, Infineon, Qimonda, and imec. Altimime holds an MSc from Heriot-Watt University, Scotland.

References

Opening Remarks

A. Manocha
President and CEO
SEMI, Milpitas, United States of America



Abstract

Opening Remarks

Biography

Throughout his career, Ajit Manocha has been a champion of industry collaboration as a critical means of advancing technology for societal and economic prosperity. He has been adept at forming strong partnerships with customers, suppliers, governments, academia, and communities for these efforts. In his current role as President and CEO of SEMI, the global industry association serving the electronics manufacturing supply chain, Manocha has positioned the organization to tackle major challenges facing the industry by building up workforce development programs to address its growing talent shortage and lack of gender parity.

Previously, he held senior worldwide operations leadership roles at Philips Semiconductors (NXP) and Spansion before serving as President and CEO at GLOBALFOUNDRIES. He has served on the boards of SEMI, SIA, and GSA.

Manocha began his career as a research scientist at AT&T Bell Laboratories, where he was granted over a dozen patents related to semiconductor manufacturing processes that served as the foundation for modern microelectronics manufacturing.

Manocha was an advisor to President Obama on the Advanced Manufacturing Partnership Steering committee and on the President's Council of Advisors on Science and Technology (PCAST). In 2012, during his tenure at GLOBALFOUNDRIES, he was awarded the prestigious "EHS Achievement Award — Inspired by Akira Inoue" for his commitment and action on Environmental Health and Safety standards. Additionally, he has excelled in people development by teaching courses such as "Leadership by Example" and "Classroom to Cleanroom to Boardroom."

In December 2019, Manocha was named an "All Star of the Semiconductor Industry" by VLSI Research for his visionary leadership in restructuring SEMI from its traditional position to represent the expanded electronics supply chain. In February 2020, he was inducted into the Silicon Valley Engineering Hall of Fame.

References

European Semiconductor Policies: Towards Chips Act 2.0

P. Chastanet
Head of the Unit for Microelectronics and
Photonics
European Commission, Brussels, Belgium



Abstract

Semiconductors are increasingly recognised as critical to the EU's economic security. Economic security is increasingly a policy area that is being coordinated by the EU, especially in light of current geopolitical instability. The strategic importance of semiconductors extends across numerous sectors and impacts all Member States, regardless of the size of their domestic semiconductor industries.

To secure the EU's position in future-defining technologies (e.g. chips for Artificial Intelligence) and to promote the EU's strategic autonomy, action at EU level is vital in order to leverage the Single Market and jointly devise solutions to address dependencies in leading-edge chips. The EU can, by enabling joint action and increased coordination, pool the strengths of different Member States in the various segments of the semiconductor value chain. These actions will help safeguard critical industrial sectors, ensure that the EU can sustain its digital transition, and enable future EU markets of leading-edge chips – including AI chips for data centres (cloud/edge) and high-performance computing infrastructures (e.g. AI factories and gigafactories).

The revision of the Chips Act is intended to ensure the EU's resilience and technological sovereignty in semiconductor technologies and applications.

Biography

Pierre Chastanet is Head of the Unit for Microelectronics and Photonics at the European Commission, where he manages the development of European semiconductor policy and the implementation of the European Chips Act.

Mr. Chastanet has been working for over 18 years in the European Commission, supervising different digital policies in the areas of cloud, data flows, software, cybersecurity, privacy, green ICT, and telecom innovation.

Prior to that, Mr. Chastanet gained more than 10 years of ICT experience, mostly in various IT management positions in a large multinational company.

He graduated from Telecom ParisTech, the Free University of Brussels, and the London School of Economics and Political Science. He also earned a Leadership Executive Certificate from Harvard Kennedy School of Government.

References

It's Time to Futureproof our Prosperity by Superfueling Innovation, Enabling Next-Gen AI

L. Van den hove
President & CEO
imec, Leuven, Belgium



Abstract

The AI field is evolving at an incredibly fast pace, with major models and updates being released almost every month. As these models evolve beyond Large Language Models towards next-gen AI with advanced reasoning capabilities, compute systems struggle to handle the heterogeneous workloads in a performant and sustainable way. However, developing new, AI-optimized compute architectures and the enabling semiconductor technologies takes much more time than writing algorithms. To prevent bottlenecks slowing down AI-based advancements, we must reinvent compute architectures and semiconductor technology platforms.

The presentation will shed light on the need for flexible, versatile compute architectures implemented in flexible, versatile technology platforms while addressing the increasing challenges of density, power and memory. To speed up both advanced semiconductor technology R&D and full stack innovation for future AI applications, imec is expanding its pilot line infrastructure under the EU Chips Act. Next to new infrastructure, imec aims to boost innovation through intensified collaborations with complementary knowledge partners and through further internationalization, attracting global talent and building strong, local ecosystems for diverse application domains, like health and automotive.

Transformative innovations for humankind hinge on the innovation pace of the semiconductor industry. It's time to supercharge our innovation engine, it's time to futureproof our prosperity.

Biography

Luc Van den hove is President and CEO of imec since July 1, 2009. Before he was executive vice president and chief operating officer. He joined imec in 1984, starting his research career in the field of silicide and interconnect technologies.

In 1988, he became manager of imec's micro-patterning group (lithography, dry etching); in 1996, department director of unit process step R&D; and in 1998, vice president of the silicon process and device technology division. In January 2007, he was appointed as imec's EVP & COO. Luc Van den hove received his PhD in electrical engineering from the KU Leuven, Belgium.

In 2023, he was honored with the Robert N. Noyce medal for his leadership in creating a worldwide research ecosystem in nanoelectronics technology with applications ranging from high-performance computing to health.

In 2025, he was awarded the honorary distinction from the Flemish Community in recognition of his impressive role in strengthening Flanders as a leading innovative region.

He has authored or co-authored more than 200 publications and conference contributions.

References

Precision at Scale: How Europe Builds Its Wafer Fabs

H. Blaschitz
Executive VP of Advanced Technology Facilities
Exyte, Singapore, Singapore



Abstract

Europe is entering a new era of semiconductor manufacturing - one defined by precision at scale. This presentation explores how European engineering and construction teams are demonstrating the capability to deliver world-class wafer fabs that meet the highest standards of sustainability, safety, and technical precision.

Significant progress has been made in execution speed, quality, and digitalization, proving that Europe can build competitively on the global stage.

At the same time, higher construction and labor costs continue to challenge competitiveness and demand new levels of efficiency, modularization, and collaboration across the supply chain.

Europe's journey is still unfolding - yet its focus on innovation, reliability, and long-term value is shaping a distinctly European approach to building the world's most advanced factories.

Biography

Herbert Blaschitz, Executive VP of Advanced Technology Facilities at Exyte, is a recognized leader in the semiconductor industry. He has played a pivotal role in the profitable expansion of Exyte's semiconductor business, growing it from 1 billion euros in 2014 to over 6 billion euros in 2023.

Before joining Exyte, he held various positions at Jenoptik, Asyst, and Siemens Semiconductor (now Infineon). Originally from Austria, Herbert has lived and worked in Germany, France, the USA, and currently resides in Singapore.

Herbert Blaschitz earned a degree in electrical engineering from HTBL of Klagenfurt, Austria, and a degree in business administration from GSBA in Zurich, Switzerland.

References

Powering the AI Era: A Collaborative Path to Sustainable Semiconductor Growth

H. Berthe
President of the Semiconductor Segment
Schneider Electric, Paris, France



Abstract

The semiconductor industry stands at a pivotal moment: AI is driving unprecedented energy demand, while climate goals demand urgent decarbonization. Addressing this dual challenge requires more than innovation—it demands collaboration.

In this session, Schneider Electric, joined by Applied Materials, explores how cross-industry partnerships are reshaping the energy landscape for semiconductors. From grid decarbonization and compute efficiency to supplier enablement and shared digital platforms, the focus is on scalable, systemic change. Real-world initiatives—like joint Scope 2 programs, standardized energy audits, and renewable access for upstream suppliers—demonstrate how collective action can accelerate progress.

The path forward is clear: by aligning on metrics, transparency, and policy, the industry can build a resilient energy foundation for the AI era—one that's clean, intelligent, and built together.

Biography

Henri Berthe, an accomplished professional with two decades of experience at Schneider Electric, is currently heading the global Semiconductor and Battery Segment. With his expertise and vision, Henri is helping to shape the future of the semiconductor and battery industry, paving the way for a more sustainable, digitized, and prosperous tomorrow.

Throughout his career, Henri has held various leadership positions within Schneider Electric, including Vice President of Universal Enclosures, where he oversaw a global business focused on high-quality, standard, and connected enclosures for electrical distribution, industrial automation applications, and data networks. He also served as Vice President of Digital Energy in the MENA and African regions, deploying digital technologies and electrification solutions in the building segment.

In May 2024, Henri was appointed as a board member of the Regional Advisory Board of SEMI South-East Asia and is part of the Global Council of the Semiconductor Climate Consortium. With an extensive background in managerial roles across different markets, Henri brings a wealth of expertise to his current role. He is a recognized authority in energy management, digital power, building management systems, and software business, holding a master's degree in Sales and Marketing from France's ESTA Belfort (Ecole Supérieure des Technologies et des Affaires).

References

Strengthening Europe's Semiconductor Ecosystem: The Role of ESMC

C. Koitzsch
President and Managing Director
European Semiconductor Manufacturing
Company (ESMC), Dresden, Germany



Abstract

As Europe intensifies its efforts to strengthen its technological sovereignty and resilience, the establishment of ESMC – a joint venture of TSMC, Bosch, Infineon and NXP – in Dresden marks an important milestone for the continent's semiconductor industry. With this €10 billion venture, the company not only builds one of Europe's largest and most advanced semiconductor fabs but also creates a vibrant hub for semiconductor talent and innovation. Global collaboration stands at the core of this initiative: Its success is the direct result of the joint efforts of numerous companies and sets new benchmarks for partnership and sustainability – from pioneering green energy and resource efficiency to engaging with industry, academia and local communities. In this way, ESMC helps pave the way for a resilient, future-ready European ecosystem where innovation and sustainability thrive.

Biography

Dr. Christian Koitzsch has been the president and managing director of the European Semiconductor Manufacturing Company (ESMC) since beginning of 2024. He was raised in Thuringia, is married and is father of two children. He studied Electrical Engineering at Technische Universität Ilmenau and North Carolina State University in Raleigh (US) and received a PhD in solid state physics from the University of Neuchâtel, Switzerland.

References

From Atoms to Algorithms: European Suppliers' Technological Race to Stay Ahead in the Semiconductor Market

A. Grede
CTO
Comet, Geneva, Switzerland



Abstract

The semiconductor industry is accelerating into a new era, where breakthroughs are measured not only in nanometers but in the intelligence of entire systems. From the atomic scale of advanced materials to the power of algorithms in manufacturing and AI, the pace of change is relentless.

For European suppliers, the stakes have never been higher. Global rivals are scaling fast, customers are insourcing more than ever, and complexity itself has become the ultimate competitive edge.

In this environment, suppliers can no longer rely on products alone. Relevance will come from anticipating what customers need before they ask, being the trusted partner when complexity turns into risk, and unlocking the power of data to create intelligence that shapes the next generation of solutions.

Comet's CTO André Grede will chart the landscape ahead and invite us to rethink how European suppliers can turn today's pressure into tomorrow's advantage turning customer trust, early collaboration, and data-driven insight into their strongest competitive advantages.

Biography

André Grede is a seasoned technology leader with a deep background in electrical engineering and a passion for driving innovation in the semiconductor industry. He graduated in Electrical Engineering (Diplom-Ingenieur), specializing in high-frequency technology, from the Berlin Institute of Technology, where he began his career as a research associate in electrodynamics.

In 2011, André joined TRUMPF Hüttinger in Freiburg as a Team Leader in R&D, later advancing to Head of the RF Product Development Group. His expertise in radiofrequency (RF) technologies brought him to Comet in 2015, where he served as Vice President of Global R&D and Technology for Plasma Control Technologies. In this role, he shaped the division's technology and product roadmap for RF subsystems, a cornerstone of modern semiconductor manufacturing.

Since 2023, André has been serving as Chief Technology Officer of Comet Group. With his pioneering spirit and forward-looking vision, he is driving the company's transformation from a manufacturing-centered organization to one that fully integrates software and digital intelligence, positioning Comet as a key partner in the fast-evolving semiconductor landscape.

References

Engineered Substrates: Powering Connectivity, Mobility, and Sustainability

C. Maleville
Chief Technology Officer
Soitec, Paris, France



Abstract

Engineered substrates, including advanced technologies like Silicon-on-Insulator (SOI), Piezo-on-Insulator (POI), and SmartSiC™, are fundamental enablers for the next generation of electronics, directly addressing the demands of a hyper-connected and mobile world while driving sustainability. These advanced materials optimize semiconductor performance by reducing power consumption and enhancing speed and integration. For connectivity (5G/6G, IoT), they enable high-performance, energy-efficient radio frequency (RF) front-end modules, with POI being pivotal for filters. Crucially, in AI computing, the synergy of SOI with silicon photonics is transforming data centers by integrating high-speed optical data transmission directly on-chip, drastically lowering latency and energy consumption. In mobility (electric vehicles, autonomous driving), SmartSiC™ substrates underpin robust, high-voltage power electronics, significantly boosting vehicle range and battery charging efficiency by utilizing a thin, high-quality SiC layer on an engineered handle wafer. By offering superior performance per watt across all these domains, these substrates are essential for building a more efficient, capable, and sustainable future.

Biography

Christophe Maleville has been appointed Chief Technology Officer and Senior Executive Vice President of Soitec's Innovation.

He joined Soitec in 1993 and was a driving force behind the company's joint research activities with CEA-Leti. For several years, he led new SOI process development, oversaw SOI technology transfer from R&D to production, and managed customer certifications. He also served as vice president, SOI Products Platform at Soitec, working closely with key customers worldwide.

Maleville has authored or co-authored more than 30 papers and also holds some 30 patents. He has a PhD in microelectronics from Grenoble Institute of Technology and obtained an executive MBA from INSEAD.

References

Executing the European Chips Act with Speed and Impact: CEA-Leti's Pilot Line Fueling Industry Growth and AI Innovation

S. Dauvé
CEO
CEA-Leti, Grenoble, France



Abstract

CEA-Leti plays a key role in executing the European Chips Act through the fast deployment of its advanced pilot line. By accelerating innovation in FDSOI and energy-efficient heterogeneous technologies, CEA-Leti supports the growth of Europe's semiconductor industry. These breakthroughs enable the next generation of AI and datacom applications while strengthening Europe's technological sovereignty. With speed, collaboration, and industrial impact, CEA-Leti turns vision into tangible results for a sustainable digital future.

Biography

Sebastien Dauvé started his career at the French Armament Electronics Center, where he worked on developing synthetic-aperture radar. In 2003, he joined CEA-Leti as an industrial transfer manager and supervised several joint research laboratories, in particular with the multinational Michelin.

In 2007, Sebastien Dauvé became a laboratory manager, then head of an R&D department in the area of sensors applied to the Internet of things and electric mobility. During this time, he supported the dissemination of new technologies in industry, including the automotive industry (Renault), aeronautics, national defense (SAFRAN), and microchips with the industry leader Intel. He played an active role in the creation of start-ups in application fields ranging from health to infrastructure security, leading to dozens of new jobs. In 2016, he became Director of the CEA-Leti Systems Division.

From sensors to wireless communication, Sebastien Dauvé has played an active role in the digital transformation, focused on coupling energy frugality and performance. He has made cross-disciplinary approaches central to innovation by harnessing the expertise of talented teams with diverse backgrounds. Their goal is to provide technological tools for meeting the major societal challenges of the future.

Sebastien Dauvé is a graduate of the prestigious French Ecole Polytechnique and the National Higher French Institute of Aeronautics and Space (ISAE-SUPAERO).

References

Chips and sovereignty: Europe's race to compete

N. Haddaoui
Managing Director
European economics, Paris, France



Abstract

The semiconductor industry has entered a new era where sovereignty, not globalisation, defines competitiveness.

Across the world, governments are racing to subsidise production and secure their supply chains.

Europe is responding with its own model of strategic investment, from the EU Chips Act to IPCEI, combining public and private forces through true economic engineering.

Yet Europe must now accelerate execution to transform vision into reality.

In this session, Narjiss Haddaoui from european economics will explore how public funding is reshaping Europe's semiconductor ambitions and why mastering its dynamics is essential to remain competitive in the global race.

Biography

Narjiss Haddaoui is Managing Director at european economics, a leading consultancy specialised in State aid and European funding.

A graduate of Paris Dauphine University with a Master's in International Business, she has worked across aeronautics and nuclear industries before joining european economics in 2018.

At european economics, Narjiss leads the firm's strategic development and international expansion, strengthening its role as a bridge between public policy, finance, and industry.

She brings a forward-looking perspective on how Europe can turn public funding into a driver of industrial competitiveness, decarbonisation and sovereignty.

References

Topic Coming Soon

O. Schenk
Member of the European Parliament
European Parliament, Brussels, Belgium



Abstract

Coming Soon

Biography

Oliver Schenk is a Member of the European Parliament (EPP Group, Germany), where he works on industrial policy, digital transformation, and Europe's long-term technological competitiveness. As a member of the Committee on Industry, Research and Energy (ITRE), he is engaged in key legislative files related to critical technologies, advanced manufacturing, and Europe's digital resilience. His work focuses on strengthening Europe's capacity to innovate, reducing strategic dependencies, and supporting a European robust, interconnected ecosystem.

Before joining the European Parliament, Oliver Schenk held senior ministerial positions in the Free State of Saxony, including serving as State Minister and Head of the State Chancellery, where he oversaw strategic coordination of government policy, digitalisation initiatives, and regional economic development. In this role, he worked closely with Saxony's high-tech industries and research institutions, playing a central part in strengthening the region's microelectronics ecosystem.

His work in Parliament aims to build on this experience by supporting advancing innovation-friendly regulation and promoting strong regional technology clusters.

References

Bavaria - Powering Europe's Microelectronics

J. Schulze
Spokesperson for the Bavarian Chips Alliance,
Director of the Fraunhofer IISB
Bayern Innovativ GmbH, Munich, Germany



Abstract

Bavaria is one of Europe's leading regions in microelectronics. This presentation offers an overview of its dynamic semiconductor ecosystem, highlighting key players and initiatives such as the Bavarian Chips Alliance. A central focus is on government support measures that strengthen Bavaria's global position - ranging from talent attraction and workforce development to substantial public funding for research and development. The presentation also explores strategic technology areas where Bavaria plays a pioneering role, including semiconductor solutions for AI applications and the development of advanced chiplet technologies.

Biography

Experienced Semiconductor Physicist and Engineer with a demonstrated history of working in the research industry and academia. Skilled in Research and Development (R&D) for semiconductor-based Micro, Nano, Opto, Power, Quantum Electronics. Experienced Lecturer and Teacher in Experimental Physics, Semiconductor Physics-Engineering-Technolog

References

Innovate Together: Singapore as Your Bold, Strategic and Trusted Semiconductor Partner

T. Gan
Executive Director
Institute of Microelectronics, Singapore,
Singapore



Abstract

The semiconductor industry is growing at an accelerated pace, with AI being the key driver. In just five years, it is expected to add US\$400 billion in revenue – growth that previously took 25 years to achieve. However, next-generation semiconductor technologies demand multi-domain expertise and specialised infrastructure beyond the reach of individual companies. Even as semiconductor companies invest almost a fifth of their revenue in Research and Development (R&D), the increasing complexity and pace of innovation are challenging the limits of what companies can address on their own.

In this high-stakes environment, collaboration defines competitiveness. Companies that tap into bold, strategic and trusted innovation hubs can move faster, reduce risks, and explore new growth opportunities with confidence. Singapore exemplifies this approach. As an integral part of the global semiconductor supply chain, Singapore accounts for approximately 10% of the world's semiconductor output and 20% of all global semiconductor equipment. Singapore also hosts a thriving semiconductor R&D ecosystem, with the Agency for Science, Technology and Research (A*STAR) Institute of Microelectronics (IME) at its heart.

At A*STAR IME, we provide world-class research expertise and production-grade infrastructure that enable industry partners to tackle shared technology challenges through collaborative, risk-sharing partnerships. This session explores how companies can leverage Singapore's R&D capabilities to stay competitive in an era where speed, resilience, and collaboration will define the next wave of global semiconductor leadership.

Biography

Mr Terence Gan is the Executive Director of the Institute of Microelectronics, Agency for Science, Technology and Research.

Terence was previously from the Singapore Economic Development Board (EDB), where he was the Senior Vice President and Head of the Semiconductor Industry Group and worked closely with top local and international semiconductor companies to facilitate their investments and transform their operations in Singapore. Prior to this role, he was the Senior Vice President for Europe, Director of EDB's Electronics Cluster and a Centre Director (San Francisco).

He received his Bachelor of Science and Master of Engineering in Electrical Engineering from the Massachusetts Institute of Technology (MIT), USA.

References

Boosting Chip Capacity in Europe

M. Horstmann
General Manager and Senior Vice President
GlobalFoundries, Dresden, Germany



Abstract

Coming Soon

Biography

Manfred Horstmann serves as General Manager and Senior Vice President at GlobalFoundries (GF), overseeing European fabs, including GF's 300mm manufacturing facility in Dresden. He also leads the GlobalFoundries Engineering Services (GFES) teams in Singapore, Penang, Bangalore, and Malaysia, supporting GF's global manufacturing operations.

Since 2020, he has transformed the Dresden Fab cluster into Europe's largest 300mm wafer facility, achieving a two and a half output increase in less than three years, boosting productivity and strategically optimizing operations. He and his team led the development and production of a highly differentiated technology portfolio (55nm-22nm) for applications in fast growing markets such as automotive, MCUs, display drivers, audio amplifiers, security chip cards, radio frequency (RF) and 5G technology.

With over 27 years of experience in multiple leadership positions in spanning research, technology development, product engineering, and large-scale operations, Mr. Horstmann has held leadership roles at Advanced Micro Devices (AMD), Motorola, and IBM in Germany and the United States.

Mr. Horstmann holds over 100 patents, has authored more than 200 scientific papers and serves on advisory boards for Forschungszentrum Jülich and Nanoelectronic Materials Laboratory. Mr. Horstmann earned his Diploma and PhD in Physics from Rheinisch-Westfälische Technische Hochschule (RWTH) Aachen.

References

Positioning the Semiconductor Business and the Overall Supply Chain Resilience in Europe

F. Gualandris
President Quality, Manufacturing & Technology
STMicroelectronics, Milan, Italy



Abstract

The semiconductor industry is crucial for economic growth, especially in today's rapidly changing global landscape. Strengthening the local semiconductor supply chain requires a comprehensive approach involving infrastructure, talent, technology, and policy support.

Central to this effort is the manufacturing infrastructure in the region. Wafer fabrication facilities remain the backbone, but ultra-pure water, stable power, and advanced equipment are also required. Additionally, as chiplets and heterogeneous integration become more prevalent, the role of assembly, testing, and packaging plants for backend processes is increasingly important.

Integrating the overall semiconductor ecosystem and supply chain is a critical consideration. Companies must manage the entire process from design-in to start-of-production ensuring quality, agility and shorter execution times. Developing strong control over semiconductor manufacturing tools, introducing flexible process module design, and 3D fabs are necessary steps. This also requires reactivating raw material suppliers' capabilities, including the production of wafers, gases, chemicals, high-purity metals, and ceramics, and mastering clean room technology to reduce power and water consumption.

On the talent front, establishing a robust STEM education pipeline—covering electronics, physics, materials science, computer science, space science, neuroscience, and robotics—is a vital mid-term investment to build a skilled workforce. This workforce must be proficient in microelectronics, materials science, statistics, data management, and familiar with AI-driven manufacturing and computer science. Strengthening collaboration between R&D institutions, universities, public labs, and industry is essential to drive process innovation. Policymakers should adopt flexible and responsive governance approaches to encourage investment and effectively support the changes initiated by the semiconductor industry.

Biography

Fabio Gualandris is STMicroelectronics' President, Quality, Manufacturing, and Technology and has held this position since July 2023. He was responsible for the company's Back-End Manufacturing & Technology organization since 2016 and also led the Company's Testing Council, alongside its manufacturing strategy in Asia and efforts in System-in-Package technology. Gualandris is a member of ST's Executive Committee.

Gualandris joined SGS Microelettronica (now ST) R&D in 1984. He became R&D Director of Operations in 1989 and became Automotive BU Director in 1996. After two years as President and CEO of Semitool, he rejoined ST in 2000 as Group VP responsible for memory products including the RAM/PSRAM and Automotive Flash.

In 2005, Gualandris was appointed CEO of ST Incard, an ST smart-card subsidiary. In 2008-2010, he served as VP and Supply Chain General Manager at ST's memory JV with Intel. In 2011, Gualandris was appointed ST's Executive Vice President, Product Quality Excellence. Gualandris has authored several technical and managerial papers and holds multiple international patents. He serves as Chairman of STS, ST's manufacturing JV in China.

Fabio Gualandris was born in Bergamo, Italy, in 1959. He holds a Master's degree in Physics from the University of Milan.

Harnessing Light: Innovating and Scaling Together in the era of AI

A. Hidma
Senior Vice President EUR & US
ASML, Delft, The Netherlands



Abstract

AI is everywhere, requiring more data ingestion and compute than ever, driving a breath of applications and semicon requirements – both in leading edge and mainstream.

Core challenges for our ecosystem are energy efficiency, affordability, and scalability of new emerging markets such as photonics, engineered optics, micro-LEDs.

ASML aims to address these in our innovations & product roadmap, as well as by architecting More than Moore solutions. To strengthen Europe's competitiveness and sovereignty we encourage ecosystem collaboration across research partnerships, industrial partners and down-stream customers to speed up our learning and focus our innovation engine to make a difference.

Biography

Anne Hidma has been appointed Senior Vice President, head of Europe and US Customer Team in January 2024. She serves on ASML's executive team and is responsible for ASML's customer and research partnerships, as well as business operations across these regions.

As such, Anne's team addresses customers' future technology roadmaps, application challenges, and operational requirements.

Next to the financial and operational management of our customer business, she drives improvements in ASML's products and services together with the broader ASML organization to better meet customer needs. Prior to ASML, Anne was a Partner at McKinsey & Company where she led the Advanced Industries practice in the Benelux.

Anne obtained her MSc degree in Nanoscience at the faculty Applied Physics of Delft University of Technology. She holds an MBA degree (with honors) from Columbia University in New York.

References

Capturing Value in the Age of Compute-Enabled Intelligence

C. Frey
Vice-President of EU Engagements
Arm France, Sophia Antipolis, France



Abstract

Every industrial revolution has been powered by an engine. Today, compute drives the age of intelligence, reshaping how humans interact with technology. Early machines were human-intensive: cars needed a crank handle; PCs demanded keyboard and mouse. By the late 20th century, products became connected and reactive with touchscreens and apps. With AI, systems are shifting from reactive to proactive: autonomous companions that act for us, powered by far more compute. The next leap brings “guardian” systems that augment us demanding orders-of-magnitude more capability. Capturing value in this transition requires pairing technical breakthroughs with new business models and ecosystem structures that translate innovation into durable economic impact.

Biography

Based in Sophia Antipolis France, he has been the **General Manager of Arm France** since 2014. He also serves as **VP of EU Engagements** where he focuses on strengthening Arm’s presence within the European semiconductor ecosystem.

Prior to Arm he has held various roles in design and management at STMicroelectronics in Crolles, France, for 12 years. He contributed to establish the Crolles2 alliance with Philips and Motorola, an experience that led to his first international immersion in Austin Texas.

He then joined the startup SOISIC, where he served as VP of Engineering before the company was acquired by Arm in 2006. At Arm, he has spent four years in Silicon Valley California as VP of Operations.

In 2024 he became an operating Partner at C4 Ventures investment fund, where he brings his 30 years of experience in the semiconductor industry.

He holds a MS degree from PHELMA Grenoble.

References

Nokia's Semiconductor Technology Underpinning our Digital Society

T. Korpela
Business Development Senior Manager -
Corporate Development Organization
Nokia, Helsinki, Finland



Abstract

Semiconductor and microelectronics technology has always been at the heart of Nokia's innovation journey—starting with the invention of the transistor by Nokia Bell Labs and continuing today as we leverage advanced semiconductor technologies to power the networks that underpin our digital society. In this keynote, we will share how Nokia translates this heritage into leading technology solutions for the telecommunication, enterprise, and data center markets, and show selected technology use cases that enable advanced industrial digitalization.

Biography

Tuomas is a seasoned international business development and sales executive with 30 years of experience driving strategic growth across advanced technology sectors—including Semiconductors, Defense, Space, IoT, Cybersecurity, and Connectivity. He has led transformative initiatives for R&D groups, ICT firms, and executive teams, incl. Nokia Corporate Development.

Tuomas navigates intricate value chains and forges long-term partnerships with corporate and governmental stakeholders. His expertise spans go-to-market strategy, change management, and multicultural team leadership, with a strong foundation in value-based selling and customer-driven engagement.

References

Powering Progress: Autonomous Mobility as a Transformation Driver Across Industries

C. Senger
Member of the Board for Fully Autonomous
Mobility and Transport & CEO of ADMT GmbH
Volkswagen, Wolfsburg, Germany



Abstract

As the first tangible manifestation of Physical AI, autonomous mobility brings intelligence into the physical world—ushering in a new wave of industrial transformation. MOIA exemplifies this shift with its Autonomous Mobility Platform and Digital Twin, enabling safe and scalable operations at peak complexity. The talk outlines how Europe can lead in building a sovereign Physical AI ecosystem—supported by a strong semiconductor industry—that sets global standards for responsible innovation.

Biography

Christian Senger began his career at BMW in 1997, holding leadership roles such as Head of Energy Management and Head of BMW i Product Concepts, where he contributed to the brand's electric vehicle strategy. In 2012, he joined Continental Automotive GmbH as Head of Automotive Systems & Technology. In 2016, Senger moved to Volkswagen as Head of e-Mobility, driving the company's electric transformation. By 2019, he became a Board Member for Volkswagen Passenger Cars, responsible for Digital Car & Services, and later took over the group-wide Digital Car & Services function. Since 2020, he has led Autonomous Driving and Mobility/Transport as a Service (MaaS/TaaS) for Volkswagen Commercial Vehicles, a responsibility formalized at the Board of Management level since 2022.

References